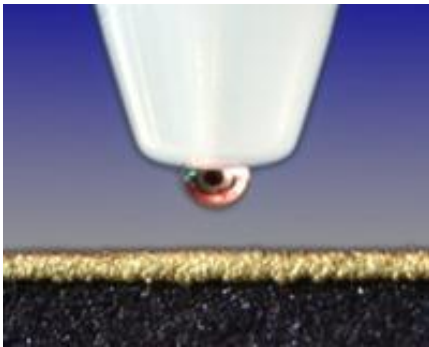


TPT-application 33 μ m copper bonding

Equipment:

- 33 μ m gold wire, 100m at 2" spool
- 33 μ m copper capillary and 33 μ gold wedge
- Semiautomatic Wire Bonder HB16



capillary



ball bonding



wedge bonding

Ball Bonding process:

- it is important that the forming gas (95%N²/5%H²) is on the tool during the EFO (TPT Copper Kit Option H47)
- need more Bond Force like Gold wire
- otherwise same process like Gold bonding.
- it is recommended to heat up bond surface up to 120°C.

Wedge Bonding process:

- need more Bond Force like Gold wire
- same process like Gold bonding.
- it is recommended to heat up bond surface up to 120°C.

Advantages over gold bonding:

- cheaper wire in mass production.
- better electronically conductivity.
- better thermal conductivity.

